

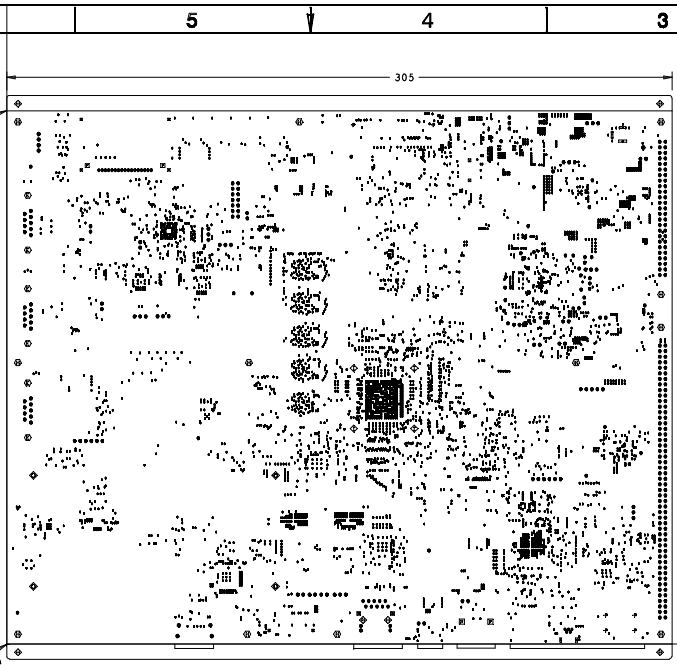
REVISIONS		DATE
REV #	DESCRIPTION	DDMMYY
REV #	CCN #	

FABRICATION NOTES:

1. EPOXY FIBREGLASS (FR-113/804) GRADE LAMINATE STRUCTURE FOR CORE AND COPPER THICKNESS TYPE GFR, GRADEA, CLASS1, CLASSA.
2. UNLESS OTHERWISE SPECIFIED ALL THE HOLE DIMENSIONS APPLY AFTER PLATING.
3. ALL PLATED THROUGH HOLES TO HAVE A MINIMUM OF 0.001" COPPER.
4. ALL HOLES SHALL LOCATE WITHIN +/-0.005" DIAMETER OF THE TRUE POSITION.
5. ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANNUAL RING AS PER IPC 6012 CLASS 2.
6. ELECTROLESS NICKEL (GOLD/NI/AU) FINISH AS PER IPC 6012 CLASS 2.
7. SPOKE SOLDERMASK OVER BARE COPPER. SOLDER MASK TO BE PER IPC-3084D, TYPE-A, CLASS 2, COLOR: TRANSPARENT GREEN.
8. SILKSREEN USING WHITE EPOXY PERMANENT, ORGANIC, NON CONDUCTIVE INK.
9. THERE SHALL BE NO SILKSREEN ON ANY SOLDERABLE COMPONENT PAD.
10. BRT TEST REQUIRED FOR SHORTS AND OPENS.
11. AUTOMATED OPTICAL INSPECTION OF ALL LAYERS IS REQUIRED.
12. WRAP OR TWIST OF BOARDS SHALL BE WITH IN IPC 6012 CLASS 2 SPECIFICATION.
13. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- CLASS 2 SPECIFICATION OF ORIGINAL ARTWORK DATA.
14. BOARD SHALL MEET THE REQUIREMENTS OF UL94 WITH A FLAMMABILITY RATION OF 94V-0, VENDORS UL LOGO SHALL BE PERMANENTLY INSERTED ON THE BOARD.
15. FABRICATION IN ACCORDANCE WITH IPC-4061, CLASS 2, PER IPC-4061.
16. BOARD SHALL BE FREE FROM FIBREGLASS DUST OR ANY OTHER FOREIGN MATERIAL.
17. PCB MUST BE FABRICATED AS PER LAYER STACKUP PROVIDED.
18. THIEVING IS ALLOWED ONLY ON PCB FRAME, NOT IN CIRCUIT AREA.
19. MINIMUM TRACE WIDTH AND SPACING: 0.084" / 0.084"
20. TEARDROPS MAY BE ADDED TO VIA PADS ON EXTERNAL AND SIGNAL LAYERS TO IMPROVE FIELDS, MAINTAINING CURRENT LINE WIDTH AND SPACING.
21. FINISHED BOARD THICKNESS: 0.78" +/- 0.01".
22. ALL VIAS SHOULD BE TREATED EXCEPT THE VIAS FOR WHICH THE SOLDERMASK IS OPEN ON BOTH THE SIDES.
23. BOARD PACKAGE MUST BE IDENTIFIED AS RAHS COMPLIANT

DETAIL-A

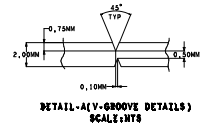
DETAIL-A



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-3.0	PLATED	1442
*	10.0	+3.0/-3.0	PLATED	3972
*	10.0	+3.0/-3.0	PLATED	30
*	28.0	+2.0/-2.0	PLATED	5
*	30.0	+3.0/-3.0	PLATED	1
*	32.0	+3.0/-3.0	PLATED	16
*	36.0	+3.0/-3.0	PLATED	10
*	40.0	+3.0/-3.0	PLATED	100
*	42.0	+3.0/-3.0	PLATED	114
*	44.0	+3.0/-3.0	PLATED	104
*	50.0	+3.0/-3.0	PLATED	4
*	52.0	+3.0/-3.0	PLATED	4
*	66.0	+3.0/-3.0	PLATED	2
*	70.0	+3.0/-3.0	PLATED	2
*	90.0	+2.3622/-2.3622	PLATED	2
*	120.0	+3.0/-3.0	PLATED	6
*	128.0	+3.0/-3.0	PLATED	12
*	34.0	+3.0/-3.0	NON-PLATED	2
*	40.0	+3.0/-3.0	NON-PLATED	4
*	42.0	+3.0/-3.0	NON-PLATED	4
*	50.0	+3.0/-3.0	NON-PLATED	2
*	62.0	+3.0/-3.0	NON-PLATED	2
*	66.0	+3.0/-3.0	NON-PLATED	4
*	128.0	+3.0/-3.0	NON-PLATED	6
*	128.0	+3.0/-3.0	NON-PLATED	4
*	140.0	+3.0/-3.0	NON-PLATED	4
*	76.0x30.0	+2.0/-2.0	PLATED	2
*	120.0x30.0	+3.0/-3.0	PLATED	1
*	120.0x30.0	+3.0/-3.0	PLATED	1
*	140.0x40.0	+3.0/-3.0	PLATED	1

LAYER STACKUP	LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS [MILS]
PRIMARY SIDE SILKSREEN				
PRIMARY SIDE SOLDERMASK				
L01	PRIMARY SIDE	1.5oz		
L02	GROUND-PLANE-1	1oz		3.296
L03	INNER-SIGNAL-1	1oz		8
L04	GROUND-PLANE-2	1oz		5.004
L05	POWER-PLANE-1	1oz		21.372
L06	POWER-PLANE-2	1oz		4
L07	GROUND-PLANE-3	1oz		5.004
L08	INNER-SIGNAL-2	1oz		8
L09	GROUND-PLANE-4	1oz		3.296
L10	SECONDARY SIDE SOLDERMASK			
SECONDARY SIDE SILKSREEN				

	TYPE	LAYER	TRACEWIDTH[MILS]	SPACING[MILS]	IMPEDANCE[Ohms]	REF LAYER
01	MICROSTRIP	L1 & L10	5.00	-	50	L02&L09
02	EDGE COUPLED MICROSTRIP	L1 & L10	5.00	5.85	85	L02&L09
03	EDGE COUPLED MICROSTRIP	L1 & L10	4.10	5.20	90	L02&L09
04	EDGE COUPLED MICROSTRIP	L1 & L10	4.00	9.00	100	L02&L09
05	STRIPLINE	L03	5.00	-	50	L04&L02
06	EDGE COUPLED STRIPLINE	L03	5.00	5.85	90	L04&L02
07	EDGE COUPLED STRIPLINE	L03	4.00	8.30	100	L04&L02
08	STRIPLINE	L08	5.00	-	50	L07&L09
09	EDGE COUPLED STRIPLINE	L08	5.00	5.85	90	L07&L09
10	EDGE COUPLED STRIPLINE	L08	4.00	8.30	100	L07&L09
11	STRIPLINE	L03	4.00	-	55	L04&L02
12	STRIPLINE	L08	4.00	-	55	L07&L09
13	MICROSTRIP	L1 & L10	4.00	-	55	L02&L09



MISTRAL SOLUTIONS PVT LTD.
 #60, ADARSH REGENT, 100' FEET RING ROAD,
 DONLUR EXTENSION, BANGALORE 560 071.

MISTRAL

TEXAS INSTRUMENTS

APPROVALS	DATE	SIZE	DRAWING NO.	REV
DESIGN: JA	100110	D	PROC046	A
CHECKED: ZA	100110			
APPROVED: AJ	100110			

SCALE: NONE FILE NAME: SHEET 1 OF 17

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